September 24, 2025

# (Progress of a Disclosed Item) Notice of the Approval of an Application for Listing on the "New Third Board" (OTC Market) in China Submitted by Our Equity-method Affiliate (Semiconductor Wafer Business)

As the progress of a disclosed matter, Ferrotec Corporation (Representative Director: He Xian Han; hereinafter "the Company") announces that the registration of Hangzhou Semiconductor Wafer Co., Ltd. (hereinafter "CCMC"), which is an equity-method affiliate of the Company, in the National Equities Exchange and Quotations (hereinafter "the New Third Board"), which is an over-the-counter market in China, was approved and it was disclosed in China on September 22, 2025.

\*Please refer to "Notice of the Acceptance of Application for Listing on the "New Third Board" (OTC Market) in China Submitted by Our Equity-method Affiliate (Semiconductor Wafer Business)" disclosed on July 3, 2025 for this matter.

### 1. Outline of the applying company as of June 30, 2025

(1)	Name	Hangzhou Semiconduct	or Wafer Co., Ltd. (CCMC)
(2)	Address	No.888 Dongken Road, Qiantang New District, Hangzhou, Zhejiang, Peoples	
		Republic of China	
(3)	Title and name of	He Xian Han, Legal repr	resentative
	representative		
(4)	Contents of business	Manufacture and sale of semiconductor wafers	
(5)	Capital	5,032 million yuan (approx. 104.8 billion yen)	
		(1 Chinese yuan = 20.82	2 yen)
(6)	Date of establishment	September 28, 2017	
(7)	Our shareholding ratio	23.05%	
	Relationship between CCMC and the Company	Capital relationship	CCMC is an equity-method affiliate of the Company.
(8)		Personnel relationship	One Director of the Company concurrently serves as the
			Representative Director of CCMC.
		Business relationship	None applicable

## 2. Future outlook and prospects

CCMC will proceed with the procedures for listing shares of CCMC in t the New Third Board, and the over-the-counter trading of the shares will begin in October 2025 at the earliest. The impact on the consolidated business performance of the Group for the current fiscal year is expected to be minor at the time of releasing this document. However, we will promptly disclose relevant items as soon as they are confirmed.

### 3. Note

Please also refer to the following materials for this matter.

Release date	Title
July 3, 2025	Notice of the Acceptance of Application for Listing on the "New Third Board" (OTC
	Market) in China Submitted by Our Equity-method Affiliate (Semiconductor Wafer Business)
July 4, 2024	Notice of the Withdrawal of a Listing Application by Our Equity-Method Affiliate (Semiconductor Wafers)
August 30, 2022	Notice of an Application for Listing on the Science and Technology Innovation Board of the Shanghai Stock Exchange by a Semiconductor Wafer Equity-Method Affiliate
October 20, 2021	Notice of the Conclusion of an Advisory Contract for Listing Between Our Equity- Method Affiliate (Semiconductor Wafer Business) and Haitong Securities Co. Ltd. (Managing Underwriter) and the Approval for Registration by the China Securities Regulatory Commission
September 15, 2021	Notice of the Completion of Payment of the (Second) Issuance of New Shares through Third-Party Allotment at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers

# News Release: Ferrotec Corporation

September 15, 2021	(Correction and Change of a Disclosed Item) Notice of the (Second) Issuance of
	New Shares through Third-Party Allotment and Capital Investment (Acquisition of
	Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor
	Wafers
July 15, 2021	(Change of a Disclosed Item) Notice of the (Second) Issuance of New Shares
	through Third-Party Allotment and Capital Investment (Acquisition of Fixed
	Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers
June 30, 2021	(Correction of a Disclosed Item) Notice of Listing of an Equity-Method Affiliate
	That Manufactures Semiconductor Wafers
June 29, 2021	Notice of Listing of an Equity-Method Affiliate That Manufactures Semiconductor
	Wafers
April 15, 2021	Notice of the (Second) Issuance of New Shares through Third-Party Allotment
	and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate
	for Manufacturing Semiconductor Wafers
February 10, 2021	Notice of Change of Specific Subsidiaries that Manufacture Semiconductor
	Wafers
November 13, 2020	(Addition/Correction of a Disclosed Item) Notice of the Issuance of New Shares
	through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor
	Wafer
November 13, 2020	(Correction of a Disclosed Item) Notice of the Completion of Payment for New
	Shares through Third-Party Allotment by the Subsidiary that Manufactures
	Semiconductor Silicon Wafers
November 5, 2020	(Correction of a Disclosed Item) Notice of the Completion of Payment of the Price
	for Transfer of Shares of the Subsidiary that Manufactures Semiconductor Silicon
	Wafers
November 2, 2020	(Progress of a Disclosed Item) Notice of the Completion of Payment for New
	Shares through Third-Party Allotment by the Subsidiary that Manufactures
	Semiconductor Wafer
October 19, 2020	(Progress of a Disclosed Item) Notice of the Completion of Payment of the Price
	for Transfer of Shares of the Subsidiary that Manufactures Semiconductor Silicon
	Wafers
October 16, 2020	Notice of the Issuance of New Shares through Third-Party Allotment by the
	Subsidiary that Manufactures Semiconductor Wafer
September 17, 2020	(Addition/Revision of Contents) Notice of Transfer of Some Shares of the
	Subsidiary that Manufactures Semiconductor Wafers
September 15, 2020	Notice of Transfer of Some Shares of the Subsidiary that Manufactures
	Semiconductor Wafers